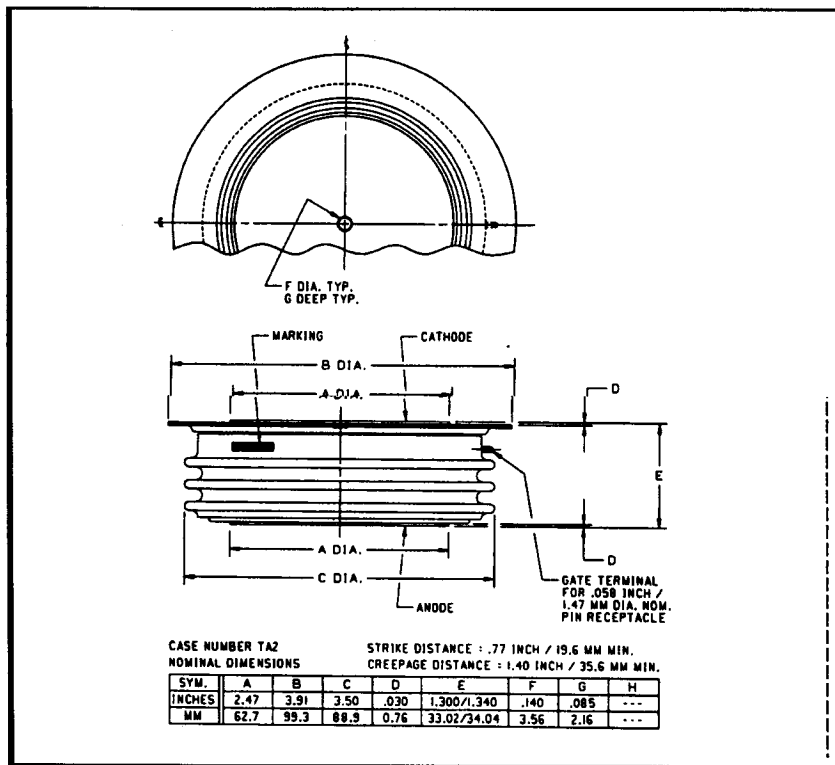
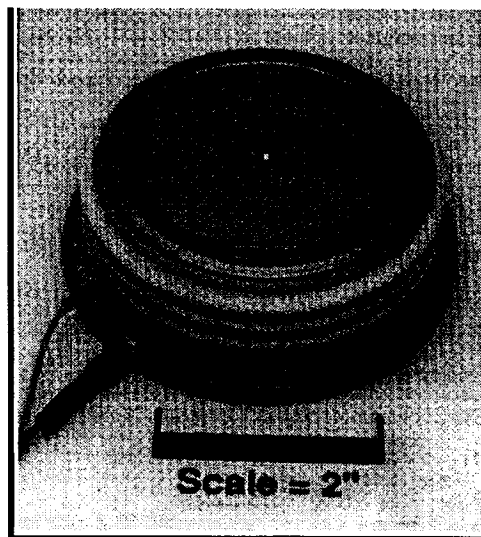


Powerex, Inc., 200 Hillis Street, Youngwood, Pennsylvania 15697-1800 (724)925-7272



Description:

Powerex Silicon Controlled Rectifiers (SCR) are designed for phase control applications. These are all-diffused, hermetic Pow-R-Disc devices employing the field-proven amplifying gate.



Ordering Information

Select the complete 12 digit device part number from the table below.

Type	Voltage V_{RM} V_{RRM}	Current I_{TSM}	Turn-Off t_r	Gate Current I_{GT}	Lead Code
TAK7	36 40 44	12	0	2	DH
	3600 V 4000 V 4400 V	1200 A	500 μ s typical	300 mA	12"

Features:

- Low On-State Voltage
- High di/dt Capability
- High dv/dt Capability
- Excellent Surge and I^2t Ratings

Applications:

- Power Supplies
- Battery Chargers
- Static VAR

Absolute Maximum Ratings

Characteristics	Symbol		Units
Non-repetitive Transient Peak Reverse Voltage	V_{RRM}	$V_{RRM}+100V$	V
Non-repetitive Transient Peak Forward Voltage	V_{DSM}	V_{DSM}	V
RMS On-State Current	$I_{T(RMS)}$	1700	A
Average Current 180° Sine Wave, $T_c=82^{\circ}C$	$I_{T(AV)}$	1200	A
Average Current 180° Sine Wave, $T_c=55^{\circ}C$	$I_{T(AV)}$		A
Peak One Cycle Surge On-State Current (Non-Repetitive) 60Hz	(60 Hz) I_{TSM}	40,000	A
Peak One Cycle Surge On-State Current (Non-Repetitive) 50Hz	(50 Hz) I_{TSM}	36,500	A
Critical Rate-of-Rise of On-State Current (Non-Repetitive) $V_{DS} > 30V$	di/dt	400	A/ μs
Critical Rate-of-Rise of On-State Current (Repetitive) $V_{DS} > 30V$	di/dt	150	A/ μs
I^2t for Fusing for One Cycle, 60 Hz	I^2t	6.87×10^4	A ² s
Peak Gate Power Dissipation	P_{GM}	16	W
Average Gate Power Dissipation	$P_{G(av)}$	3	W
Operating Temperature	T_j	-40 to 125	$^{\circ}C$
Storage Temperature	T_{STG}	-40 to 150	$^{\circ}C$
Approximate Weight		2.2 1000	lb. g
Mounting Force		9000 to 11000 4100 to 5000	lb. kg

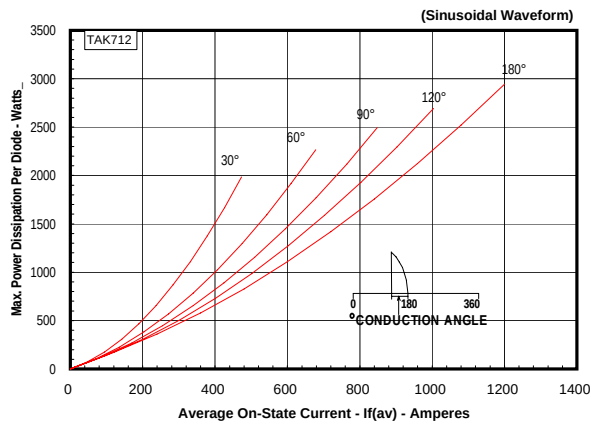
Electrical Characteristics, $T_J=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Repetitive Peak Reverse Leakage Current	I_{RRM}	$T_J=125^\circ\text{C}$, $V_R=V_{RRM}$			200	mA
Repetitive Peak Forward Leakage Current	I_{DRM}	$T_J=125^\circ\text{C}$, $V_D=V_{DRM}$			200	mA
Peak On-State Voltage	V_{TM}	$T_J=25^\circ\text{C}$, $I_{TM}=1500\text{A}$ Duty Cycle $< 0.01\%$			1.90	V
Threshold Voltage, Low-level	$V_{(TO)1}$	$T_J=125^\circ\text{C}$, $250\text{A} \leq I_{TM} < 4000\text{A}$			1.262	V
Slope Resistance, Low-level	r_{T1}				0.397	m Ω
Threshold Voltage, High-level	$V_{(TO)2}$	$T_J=125^\circ\text{C}$, $\geq 4000\text{A}$			1.412	V
Slope Resistance, High-level	r_{T2}				0.368	m Ω
ABCD Coefficients $V_{TM} = A + B \cdot \ln(I_{TM}) + C \cdot I_{TM} + D \cdot I_{TM}^{1/2}$	ABCD	$T_J=125^\circ\text{C}$			A = 2.53 B = -0.294 C = 2.47E-4 D = 0.0284	
Typical Delay Time	t_d	$I_{TM}=1000\text{A}$, $V_D=1500\text{V}$		4		μs
Maximum Turn-Off Time	T_q	$T_J=125^\circ\text{C}$, $I_T=250\text{A}$, $di_R/dt=50\text{A}/\mu\text{s}$ $dv/dt=20\text{V}/\mu\text{s}$ linear to 80% V_{DRM}		500		μs
Minimum Critical dv/dt - Exponential to V_{DRM}	dv/dt	$T_J=125^\circ\text{C}$	1000			V/ μs
Gate Trigger Current	I_{GT}	$T_J=25^\circ\text{C}$, $V_D=12\text{V}$			300	mA
Gate Trigger Voltage	V_{GT}	$T_J=25^\circ\text{C}$, $V_D=12\text{V}$			5.0	V
Non-Triggering Gate Voltage	V_{GDM}	$T_J=125^\circ\text{C}$, $V_D=V_{DRM}$			0.45	V
Peak Forward Gate Current	I_{GTM}				4	A
Peak Reverse Gate Voltage	V_{GRM}				5	V

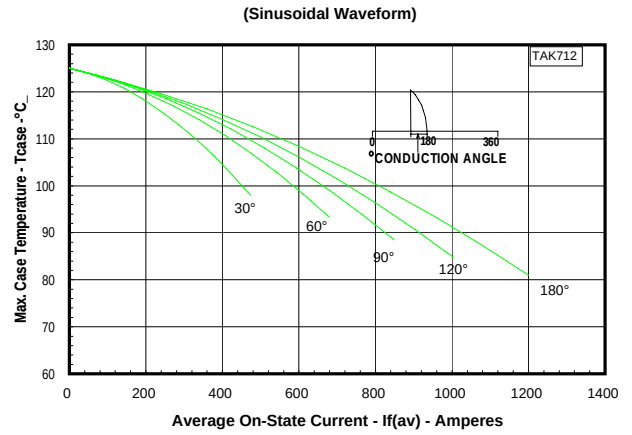
Thermal Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Units
Maximum Thermal Resistance, Double Sided Cooling					
Junction to Case	$R_{\theta JC}$			.015	$^\circ\text{C}/\text{W}$
Case to Sink	$R_{\theta CS}$			.007	$^\circ\text{C}/\text{W}$

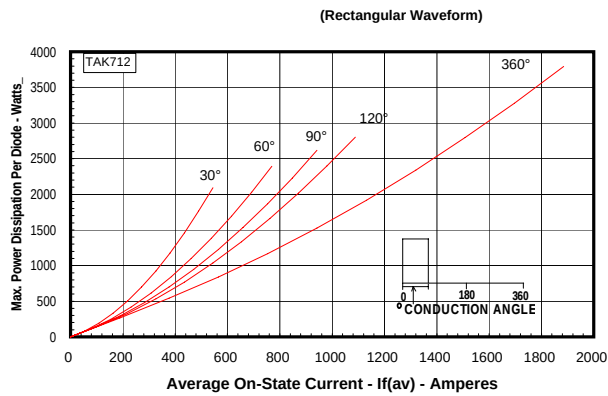
Maximum On-State Power Dissipation



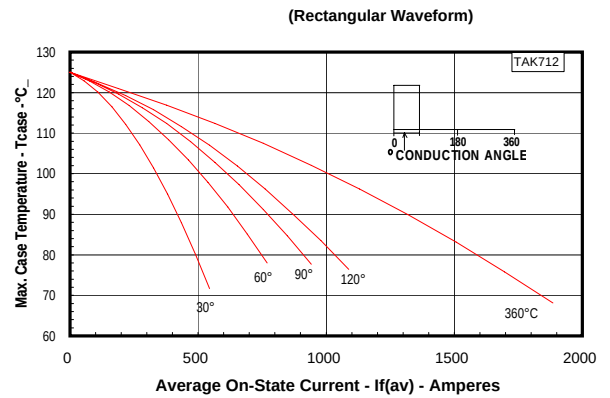
Maximum Allowable Case Temperature



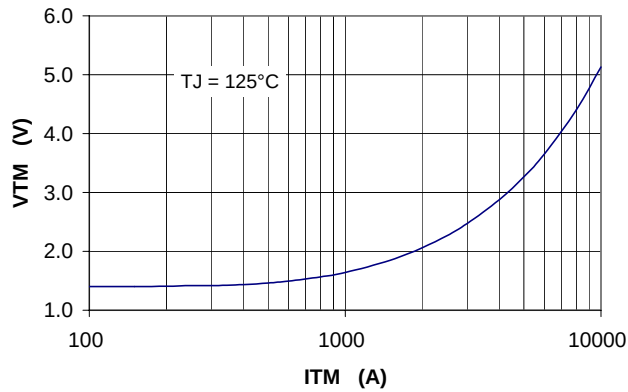
Maximum On-State Power Dissipation



Maximum Allowable Case Temperature



FORWARD VOLTAGE DROP



TRANSIENT THERMAL IMPEDANCE

